

Please replace the abstract with the following amended abstract:

Protective tape ~~[[22]]~~ is bonded onto ~~[[the]]~~ a rear surface of a semiconductor element ~~[[1]]~~ prior to ~~[[the]]~~ a resin sealing step, and then only ~~[[the]]~~ a primary surface of the semiconductor element ~~[[1]]~~ is sealed with a resin layer ~~5, so that cracks~~ . Cracks and warping which would otherwise be caused by an external force or foreign matter at ~~[[the]]~~ an exposed rear surface of the semiconductor element ~~was exposed~~~~[[,]]~~ are prevented ~~to facilitate the~~ . This facilitates a surface polishing step and also results in ~~so that~~ a lower profile is ~~achieved~~ for the semiconductor device, ~~by not sealing~~ because the rear surface is not sealed with resin.